

S9S12ZVL32F0MLC (Active)

MagniV 16-bit MCU, S12Z core, 32KB Flash, 25MHz, -40/+125degC, Automotive Qualified, QFP 32

- [Product Summary](#)
- [Software & Tools](#)
- [Documentation](#)



Package:
[LQFP](#)

plastic, low profile quad; flat leaded package; 32 terminals; 0.80 mm pitch; 7 mm x 7 mm x 1.4 mm body

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Buy Options

S9S12ZVL32F0MLC Active TRAY-Tray, Bakeable, Multiple in Drypack
 935316209557 Min. Package Quantity: 250 Lead Time: 99 weeks

[Sample](#) [Buy Direct](#) [Distributor](#) 1 @ US **\$1.53**
[Availability?](#) [Availability?](#)

S9S12ZVL32F0MLCR Active REEL-Reel 13" Q2/T3 in Drypack [Distributor](#) 1 @ US **\$1.53**
 935316209528 Min. Package Quantity: 2000 Lead Time: 99 weeks

Operating Characteristics

| Parameter | Value |
|---------------------------------|-------|
| Flash (kB) | 32 |
| RAM (kB) | 1 |
| EEPROM (kB) | 0.128 |
| Core Type | S12Z |
| Operating Frequency [Max (MHz)] | 32 |
| I ² C | 1 |

| Parameter | Value |
|-----------|-----------------------|
| SCI | 2 |
| SPI | 1 |
| GPIO | 19 |
| 5v Reg | 1 |
| HVI | 1-ch. HVI, Vsup-Sense |

Environmental Information

| Material Declaration | PbFree | EU RoHS | Halogen Free | RHF Indicator | 2nd Level Interconnect | REACH SVHC | Weight (mg) |
|---|--------|--|--------------|---------------|------------------------|----------------------------|-------------|
| S9S12ZVL32F0MLC (935316209557) | Yes | Yes Certificate Of Analysis (CoA) | Yes | D | e3 | REACH SVHC | 188.6 |
| S9S12ZVL32F0MLCR (935316209528) | Yes | Yes Certificate Of Analysis (CoA) | Yes | D | e3 | REACH SVHC | 188.6 |

Quality Information

| Material Declaration | Safe Assure Functional Safety | Moisture Sensitivity Level (MSL) | Peak Package Body Temperature (PPT) (C°) | Maximum Time at Peak Temperatures (s) |
|---------------------------------|-------------------------------|----------------------------------|--|---------------------------------------|
| | | Lead Free Soldering | Lead Free Soldering | Lead Free Soldering |
| S9S12ZVL32F0MLC | | | | |

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| S9S12ZVL32F0MLC (935316209557) | ISO 26262 | 3 | 260 | 40 |
| S9S12ZVL32F0MLCR (935316209528) | ISO 26262 | 3 | 260 | 40 |

Shipping Information

| Part Number | Harmonized Tarrif (US) Disclaimer | Export Control Classification Number (US) |
|--|---|---|
| S9S12ZVL32F0MLC (935316209557) | 854231 | 3A991A2 |
| S9S12ZVL32F0MLCR (935316209528) | 854231 | 3A991A2 |

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